BOC BGA PACKAGE FOR DIE WITH I-SHAPED BOND PAD LAYOUT

ABSTRACT

Semiconductor die units for forming BOC BGA packages, methods of encapsulating a semiconductor die unit, a mold for use in the method, and resulting encapsulated packages are provided. In particular, the invention provides a semiconductor die unit comprising an integrated circuit die with a plurality of bond pads in an I-shaped layout and an overlying support substrate having an I-shaped wire bond slot.

Figures 3A, 3B and 14B